





## United States Patent and Trademark Office

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 2023I
WWW.uspic.gov

**CONFIRMATION NO. 8260** 

Bib Data Sheet FILING DATE **ATTORNEY GROUP ART UNIT** CLASS DOCKET NO. **SERIAL NUMBER** 04/09/2001 2811 257 09/829,161 3442.1US (96-428.1) RULE APPLICANTS Salman Akram, Boise, ID; \*\* CONTINUING DATA \*\*\*\*\*\*\*\*\*\*\*\*\*\*\*\* THIS APPLICATION IS A DIV OF 09/388,031 09/01/1999 none m IF REQUIRED, FOREIGN FILING LICENSE GRANTED \* 08/30/2001 ves 🖸 no Foreign Priority claimed INDEPENDENT SHEETS TOTAL STATE OR Ves Ino Met after **CLAIMS** CLAIMS 35 USC 119 (a-d) conditions **COUNTRY DRAWING** 71 14 ID Verified and Examiner's Signature Initials Acknowledged **ADDRESS** 24247 MTLE Metallization structures for semiconductor device interconnects, methods for making same, and semiconductor devices including same All Fees 1.16 Fees (Filing) ☐ 1.17 Fees ( Processing Ext. of FEES: Authority has been given in Paper FILING FEE No. \_\_\_\_\_ to charge/credit DEPOSIT ACCOUNT No. \_\_\_\_\_ for following: time ) RECEIVED 1628 1.18 Fees (Issue) Other □ Credit